

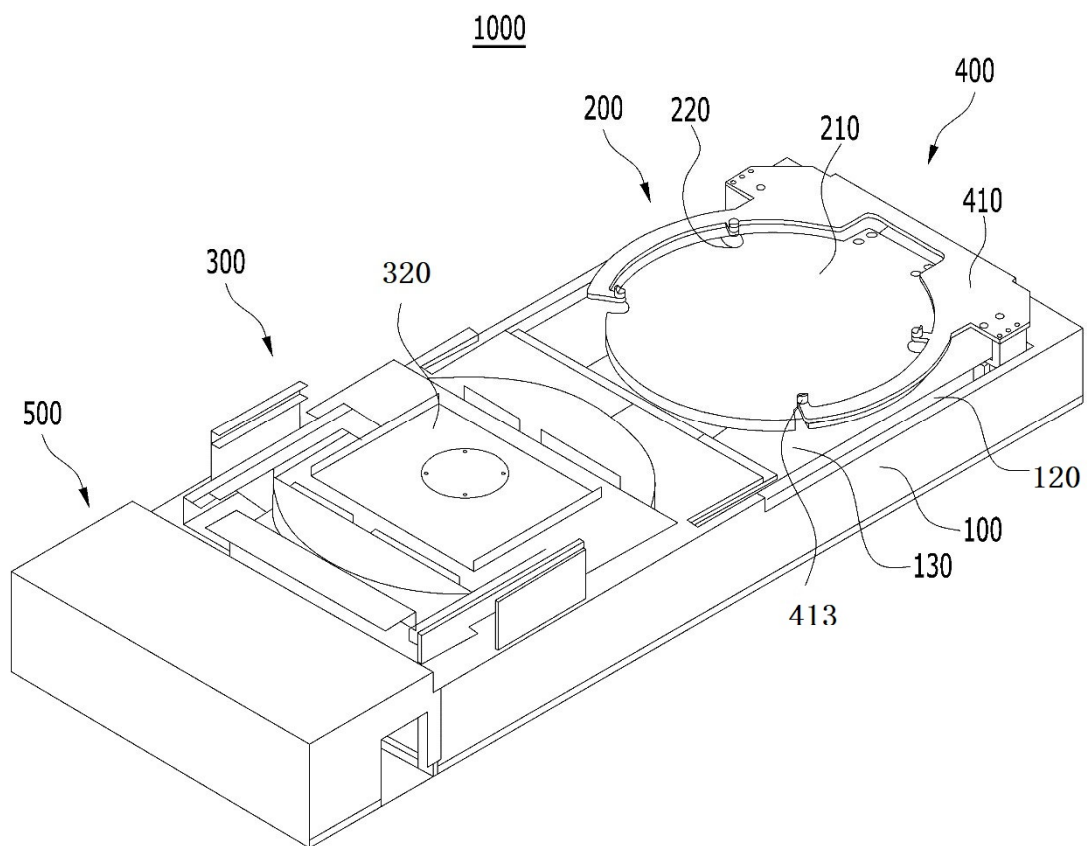


FIG. 1

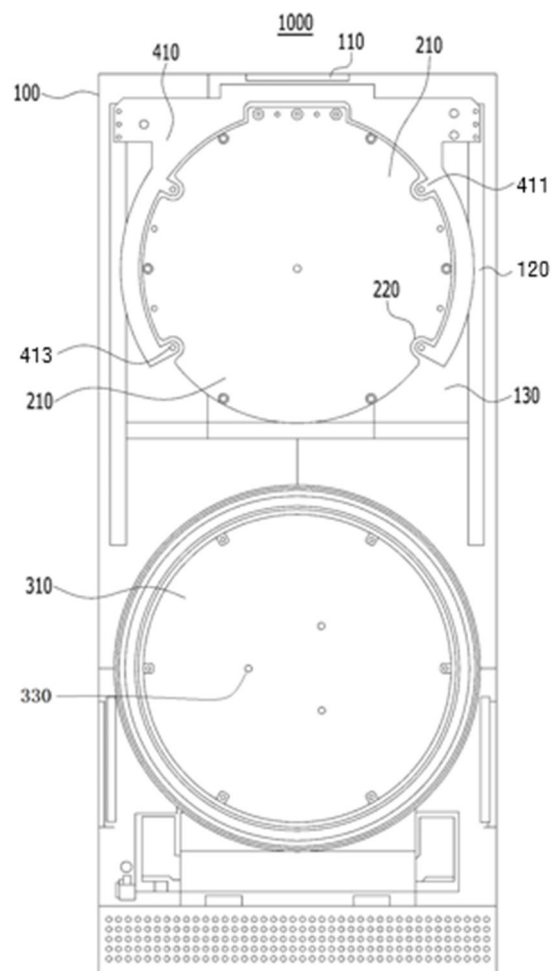


FIG. 2

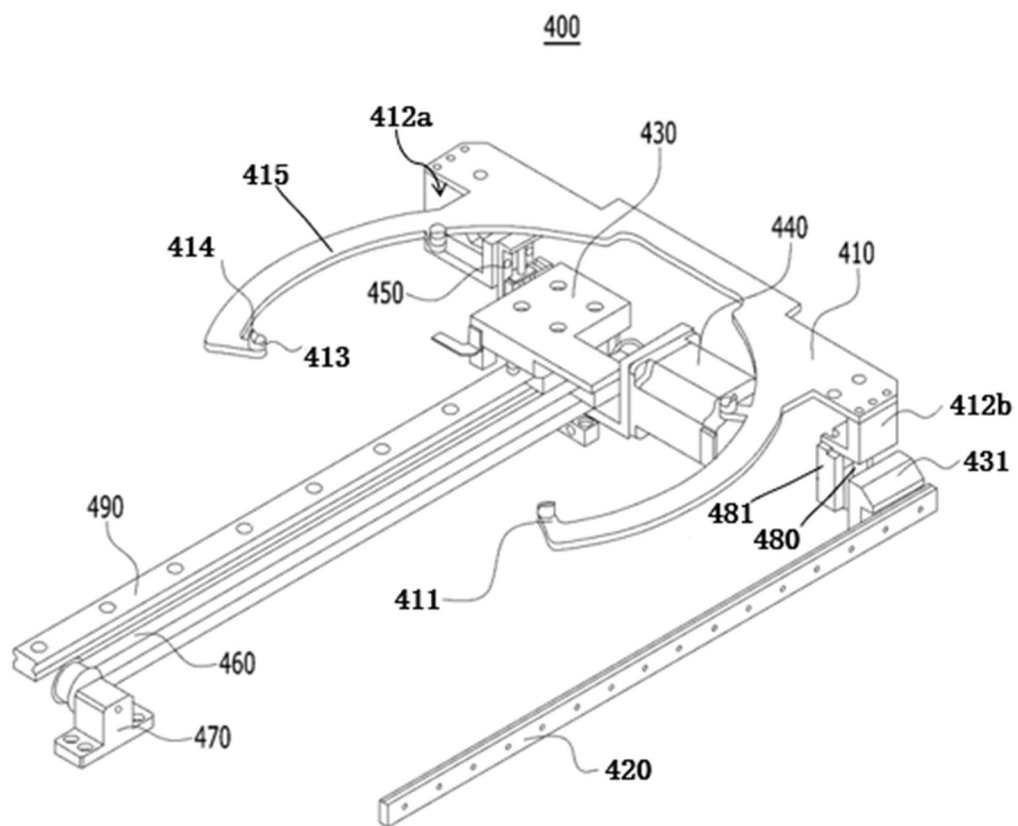


FIG. 3

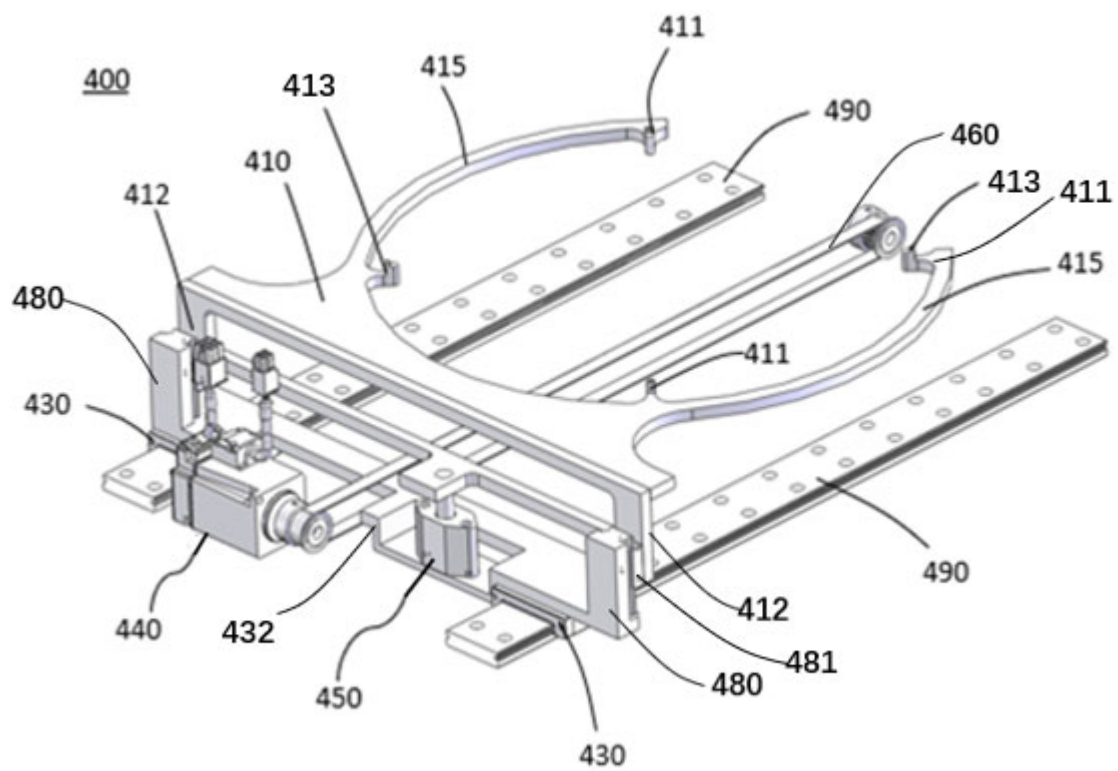


FIG. 4



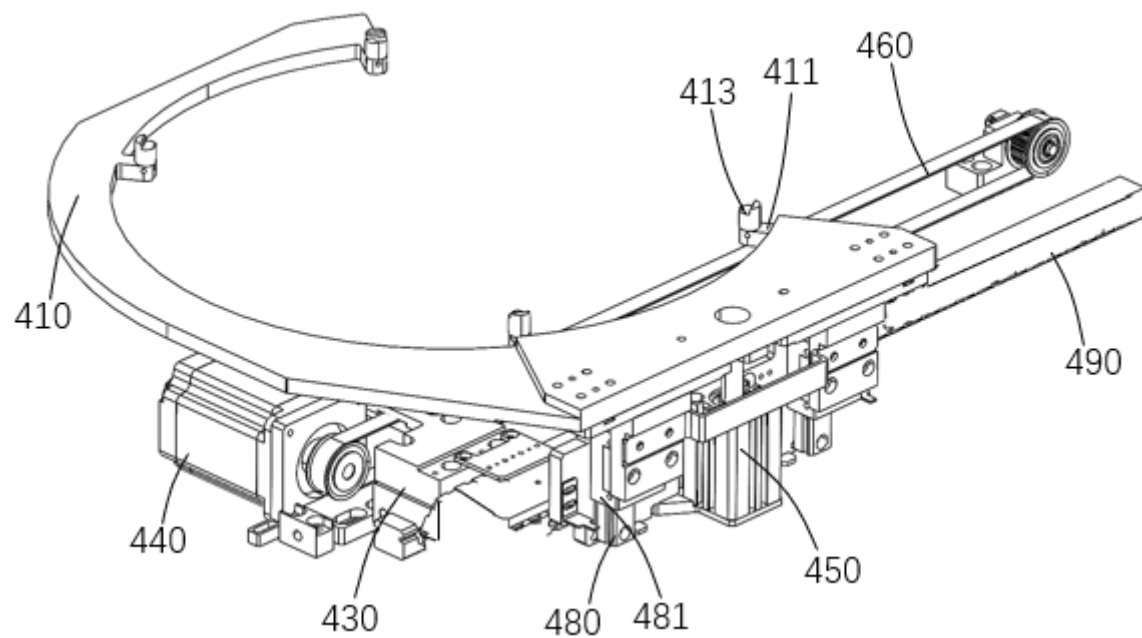


FIG. 6

S1: the first driving unit 450 drives the transmission arm 410 to ascend to a preset position, the substrate W is transmitted into the apparatus 1000 by the opening 110, and the substrate W is placed on the supporting pins 413

S2: the third driving unit drives the cover plate 320 to ascend to a preset height, and the second driving unit 440 drives the first moving member 430 to move linearly, thereby moving the substrate W to the position of heating unit 300

S3: the thimble pins 330 are ascended and extend above the heating plate 310 to receive the substrate W on the transmission arm 410, the second driving unit 440 drives the first moving member 430 back, so that the transmission arm 410 is returned to the initial position, the thimble pins 330 are descended below the heating plate 310 to transfer the substrate W onto the heating plate 310

S4: the third driving unit drives the cover plate 320 to descend, the cover plate 320 covers the heating plate 310, and the heating plate 310 starts baking the substrate W

S5: after the baking is completed, the third driving unit drives the cover plate 320 to ascend, the thimble pins 330 are ascended to push the substrate W above the heating plate 310, and the second driving unit 440 drives the transmission arm 410 to move to the heating unit 300 to receive the baked substrate W

S6: the second driving unit 440 drives the transmission arm 410 and the substrate W to move to the position of cooling unit 200

S7: the transmission arm 410 is descended below the upper surface of the cooling plate 210, the upper surface of the cooling plate 210 receives the substrate W, and the cooling plate 210 cools the substrate W

S8: after the substrate W is cooled, the first driving unit 450 drives the transmission arm 410 to ascend, firstly, the supporting pins 413 support the substrate W, and then the transmission arm 410 continues to ascend to a preset height, and the substrate W is taken away and transferred to the outside of the apparatus 1000

FIG. 7

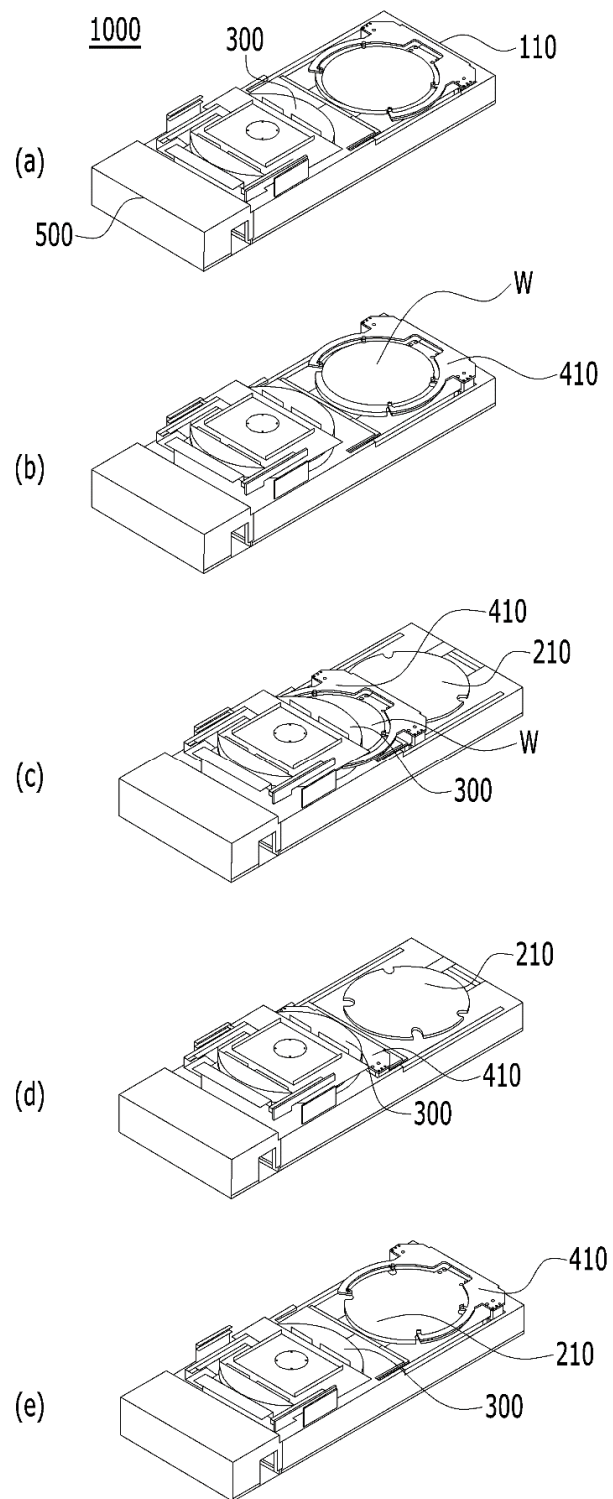


FIG. 8